

Amendments to the Claims:

Without prejudice, this listing of the claims replaces all prior versions and listings of the claims in the present application:

Listing of Claims:

1. (Currently Amended) A method for producing a conductive coating on an insulating substrate, comprising:
 - equipping, in selected regions, at least one surface of an electrically insulating substrate with a coating of an electrically highly conductive first metal, the coating being structured as conductor paths ~~a printed circuit board~~;
 - cleaning the at least one coated surface;
 - seeding the coating with seeds of a second metal;
 - depositing a layer including an alloy of the second metal onto the coating seeded with the seeds of the second metal; and
 - firing the substrate deposited with the layer of the second metal; and
 - contacting a gold bonding wire to the first metal, wherein:
 - the substrate includes one of a ceramic and an LTCC,
 - the first metal includes silver, and
 - the second metal includes palladium.
2. (Canceled)
3. (Canceled)
4. (Currently Amended) The method as recited in Claim 1 ~~3~~, wherein:
 - in the depositing of the layer of the second metal, palladium is deposited at a ratio of from 0.1 to 50% percent by weight of the alloy.
5. (Currently Amended) The method as recited in Claim 1 ~~3~~, wherein:
 - in the depositing of palladium, the palladium is deposited in such a way that a concentration of greater than 20% percent by weight palladium in the alloy results.
6. (Original) The method as recited in Claim 1, wherein:
 - the seeding and the depositing are performed according to an electroless procedure.
7. (Original) The method as recited in Claim 1, wherein:
 - the firing is performed at a temperature between 830 and 870°C.

8. (Original) The method as recited in Claim 1, wherein:
the firing is performed at a temperature of 850°C.

9.-10. (Canceled)